

# N- and P-Channel 30 V (D-S) MOSFET

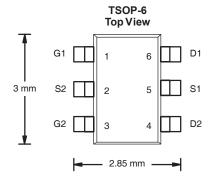
PRODUCT SUMMARY					
	V <sub>DS</sub> (V)	$R_{DS(on)}(\Omega)$	I <sub>D</sub> (A)		
N-Channel	30	0.020 at V <sub>GS</sub> = 10 V	3.7		
		$0.022$ at $V_{GS} = 4.5 \text{ V}$	3.0		
P-Channel	- 30	0.060 at V <sub>GS</sub> = - 10 V	- 3.0		
		0.079 at V <sub>GS</sub> = - 4.5 V	- 2.2		

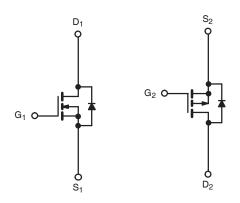
#### **FEATURES**

- DT-Trench Power MOSFET
- 100 % R<sub>g</sub> Tested
- Compliant to RoHS Directive 2002/95/EC



RoHS





N-Channel MOSFET

P-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS T <sub>A</sub> = 25 °C, unless otherwise noted						
Parameter		Symbol	N-Channel	P-Channel	Unit	
Drain-Source Voltage		V <sub>DS</sub>	30	- 30	V	
Gate-Source Voltage		V <sub>GS</sub>	± 20	± 20	V	
0 D . 0 450.003 h	T <sub>A</sub> = 25 °C	- I <sub>D</sub>	3.7	- 3.0	_	
Continuous Drain Current (T <sub>J</sub> = 150 °C) <sup>a, b</sup>	T <sub>A</sub> = 70 °C		3.0	- 2.2		
Pulsed Drain Current		I <sub>DM</sub>	8	- 7	A	
Continuous Source Current (Diode Conduction) <sup>a, b</sup>		I <sub>S</sub>	1.05	- 1.05		
a h	T <sub>A</sub> = 25 °C	D	1.15		W	
Maximum Power Dissipation <sup>a, b</sup>	T <sub>A</sub> = 70 °C	$P_{D}$	0.73			
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stg</sub>	- 55 to 150		°C	

THERMAL RESISTANCE RATINGS							
Parameter		Symbol	Typical	Maximum	Unit		
Maximum Junction-to-Ambient <sup>a</sup>	t ≤ 5 s	- R <sub>thJA</sub>	93	110			
	Steady State		130	150	°C/W		
Maximum Junction-to-Lead	Steady State	R <sub>thJL</sub>	75	90			

Notes:

a. Surface Mounted on FR4 board.

 $b.\ t \leq 5\ s.$ 

Parameter	Symbol	Test Conditions		Min.	Тур.	Max.	Unit	
Static								
Gate Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	N-Ch	0.6		1.5	V	
		V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = - 250 μA	P-Ch	- 0.6		-1.5	\ \	
Gate-Body Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$	N-Ch			± 100	nA	
		50 × 60	P-Ch			± 100		
Zero Gate Voltage Drain Current		V <sub>DS</sub> = 24 V, V <sub>GS</sub> = 0 V	N-Ch			1		
	I <sub>DSS</sub>	V <sub>DS</sub> = - 24 V, V <sub>GS</sub> = 0 V P-C				- 1	μA	
Zoro dato voltago Brain Garrent	1033	$V_{DS} = 24 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 55 ^{\circ}\text{C}$	N-Ch			5	μΑ.	
		$V_{DS} = -24 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 55 ^{\circ}\text{C}$	P-Ch			- 5		
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} = 5 \text{ V}, V_{GS} = 10 \text{ V}$	N-Ch	3.7			А	
		$V_{DS} = -5 \text{ V}, V_{GS} = -10 \text{ V}$	P-Ch	- 3				
Drain-Source On-State Resistance <sup>a</sup>		V <sub>GS</sub> = 10 V, I <sub>D</sub> = 2.5 A	N-Ch		0.020	0.024		
		V <sub>GS</sub> = - 10 V, I <sub>D</sub> = - 1.8 A	P-Ch		0.060	0.069	Ω	
	R <sub>DS(on)</sub>	$V_{GS} = 4.5 \text{ V}, I_D = 2.0 \text{ A}$	N-Ch		0.022	0.028		
		V <sub>GS</sub> = - 4.5 V, I <sub>D</sub> = - 1.2 A	P-Ch		0.079	0.083		
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 2.5 A	N-Ch		4.3		s	
		V <sub>DS</sub> = - 15 V, I <sub>D</sub> = - 1.8 A	P-Ch		2.4			
	V <sub>SD</sub>	I <sub>S</sub> = 1.05 A, V <sub>GS</sub> = 0 V	N-Ch		0.81	1.10		
Diode Forward Voltage <sup>a</sup>		I <sub>S</sub> = - 1.05 A, V <sub>GS</sub> = 0 V	P-Ch		- 0.83	- 1.10	V	
Dynamic <sup>b</sup>								
Total Gate Charge	Qg		N-Ch		2.1	3.2		
Total Gate Charge	₩g	N-Channel $V_{DS} = 15 \text{ V}, V_{GS} = 5 \text{ V}, I_{D} = 1.8 \text{ A}$	P-Ch		2.4	3.6		
Gate-Source Charge	Q <sub>gs</sub>	VDS = 10 V, VGS = 0 V, ID = 1.0 A	N-Ch		0.7		nC	
Gate-Source Charge	Q <sub>gd</sub>	P-Channel	P-Ch		0.9			
Gate-Drain Charge		$V_{DS} = -15 \text{ V}, V_{GS} = -5 \text{ V}, I_{D} = -1.8 \text{ A}$	N-Ch		0.7			
	J .		P-Ch	0.5	0.8	0.4		
Gate Resistance	$R_g$		N-Ch P-Ch	0.5 3		2.4 11	Ω	
			N-Ch	<u> </u>	7	11		
Turn-On Delay Time	t <sub>d(on)</sub>	N-Channel	P-Ch		8	12		
		$V_{DD} = 15 \text{ V}, R_L = 15 \Omega$	N-Ch		9	14		
Rise Time		$I_D \cong 1 \text{ A, } V_{GEN} = 10 \text{ V, } R_g = 6 \Omega$	P-Ch		12	18		
Time Off Dolor Time	t <sub>d(off)</sub>	P-Channel	N-Ch		13	20	1	
Turn-Off Delay Time		$V_{DD} = -15 \text{ V}, R_L = 15 \Omega$	P-Ch		12	18	ns	
Fall Time	t <sub>f</sub>	$I_D \cong -1$ A, $V_{GEN} = -10$ V, $R_g = 6$ $\Omega$	N-Ch		5	8		
		Ů	P-Ch		7	11	_	
Source-Drain Reverse Recovery Time	t <sub>rr</sub>	I <sub>F</sub> = 1.05 A, dl/dt = 100 A/μs	N-Ch		35	60		
Source-Drain Heverse Recovery Time		$I_F = -1.05 \text{ A}, dI/dt = 100 \text{ A/}\mu\text{s}$	P-Ch		30	60		

#### Notes:

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

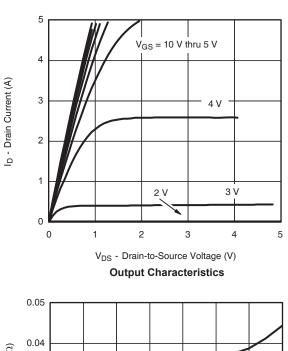
a. Pulse test; pulse width  $\leq 300~\mu s,$  duty cycle  $\leq 2~\%.$ 

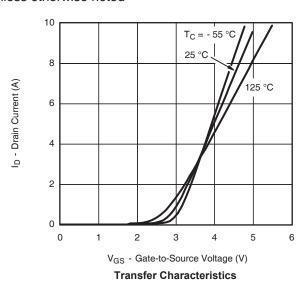
b. Guaranteed by design, not subject to production testing.

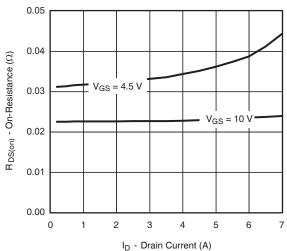


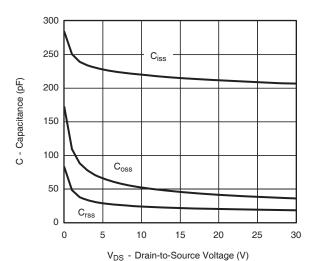
## N-CHANNEL TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

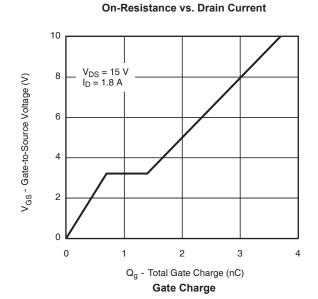
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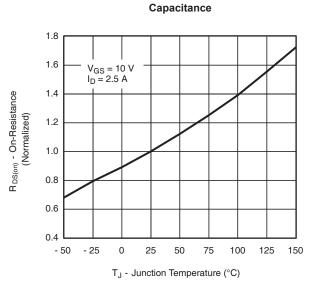










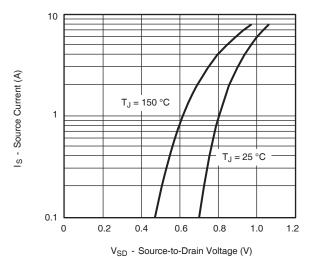


On-Resistance vs. Junction Temperature

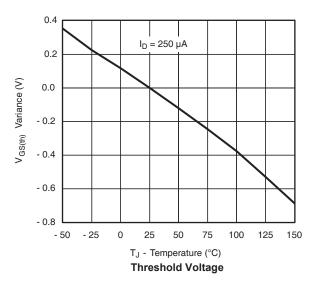


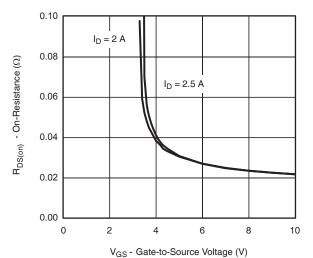
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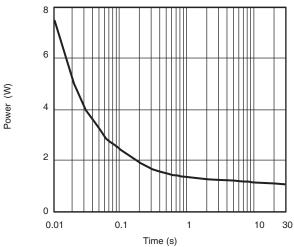


#### Source-Drain Diode Forward Voltage

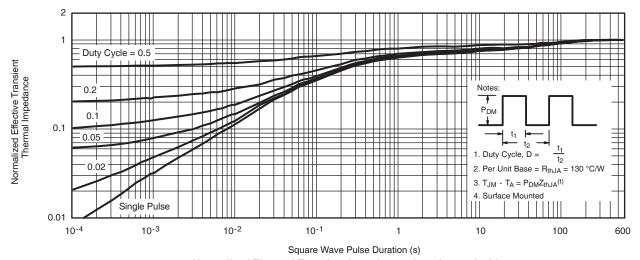




On-Resistance vs. Gate-to-Source Voltage

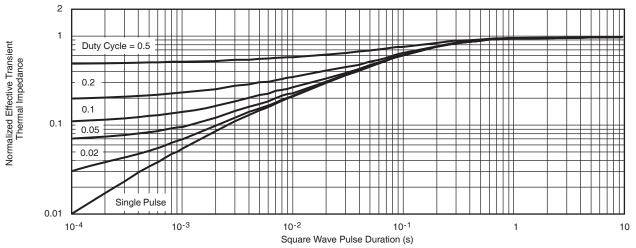


Single Pulse Power (Junction-to-Ambient)



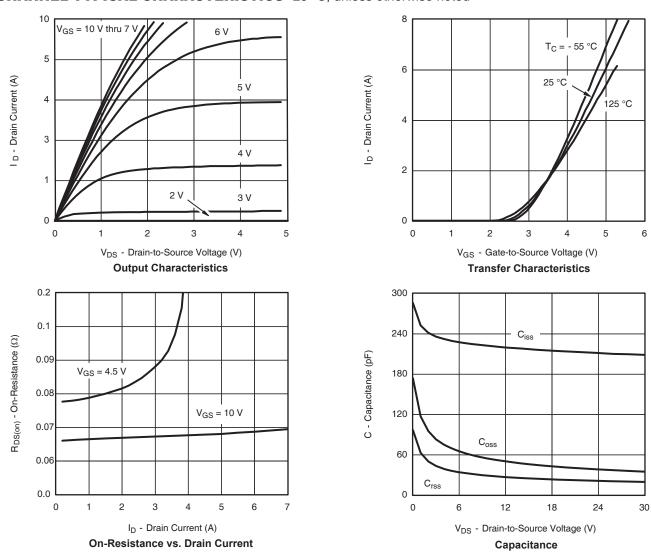
Normalized Thermal Transient Impedance, Junction-to-Ambient

#### N-CHANNEL TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



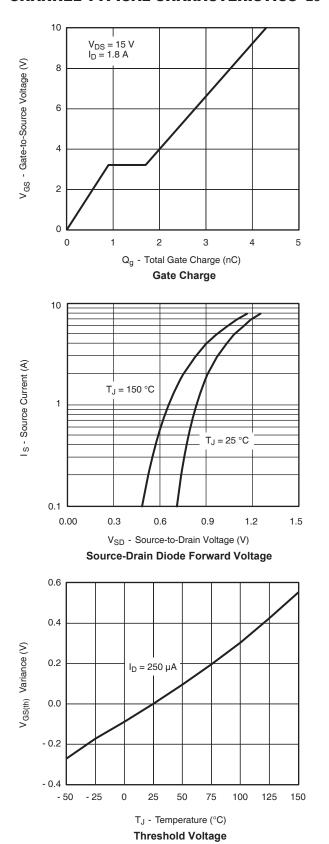
Normalized Thermal Transient Impedance, Junction-to-Foot

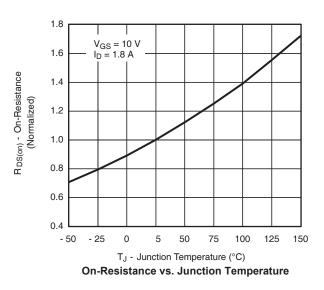
#### P-CHANNEL TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

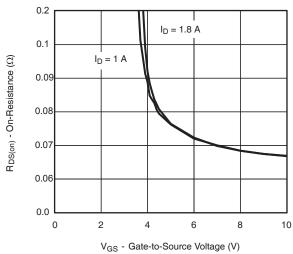


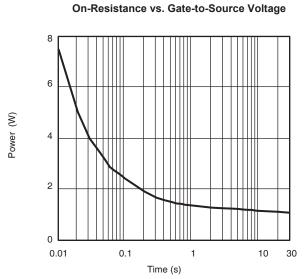
### P-CHANNEL TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

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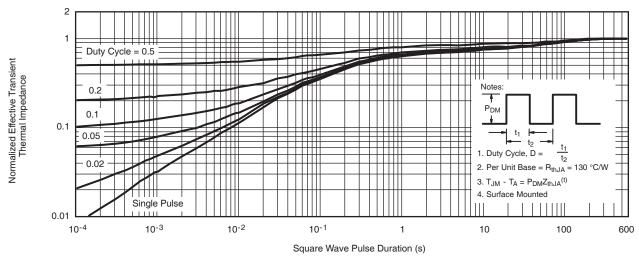




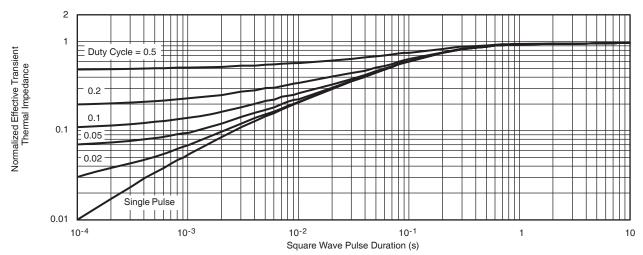


Single Pulse Power (Junction-to-Ambient)

#### P-CHANNEL TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Foot



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